



## Material Content Data Sheet



<b>Sales Product Name</b>		BTS3142D		<b>Issued</b>		27. September 2017		
<b>MA#</b>		MA001111192						
<b>Package</b>		PG-TO252-3-11		<b>Weight*</b>		392.98 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.197	1.32	1.32	13223	13223
leadframe	non noble metal	iron	7439-89-6	0.140	0.04		356	
	inorganic material	phosphorus	7723-14-0	0.042	0.01		107	
	non noble metal	copper	7440-50-8	139.706	35.56	35.61	355504	355967
wire	non noble metal	aluminium	7429-90-5	1.464	0.37	0.37	3725	3725
encapsulation	organic material	carbon black	1333-86-4	1.439	0.37		3662	
	plastics	epoxy resin	-	25.182	6.41		64081	
	inorganic material	silicondioxide	60676-86-0	117.278	29.84	36.62	298434	366177
leadfinish	non noble metal	tin	7440-31-5	3.740	0.95	0.95	9517	9517
plating	non noble metal	nickel	7440-02-0	0.091	0.02		231	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	1	232
solder	noble metal	silver	7440-22-4	0.102	0.03		260	
	non noble metal	tin	7440-31-5	0.082	0.02		208	
	non noble metal	lead	7439-92-1	3.905	0.99	1.04	9936	10404
heatspreader	non noble metal	iron	7439-89-6	0.095	0.02		241	
	inorganic material	phosphorus	7723-14-0	0.028	0.01		72	
	non noble metal	copper	7440-50-8	94.488	24.04	24.07	240442	240755
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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